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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	
Number of Logic Elements/Cells	792
Total RAM Bits	-
Number of I/O	101
Number of Gates	30000
Voltage - Supply	1.14V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	128-TQFP
Supplier Device Package	128-VTQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/aglp030v2-vqg128

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IGLOO PLUS Device Family Overview

Security

Nonvolatile, flash-based IGLOO PLUS devices do not require a boot PROM, so there is no vulnerable external bitstream that can be easily copied. IGLOO PLUS devices incorporate FlashLock, which provides a unique combination of reprogrammability and design security without external overhead, advantages that only an FPGA with nonvolatile flash programming can offer.

IGLOO PLUS devices (except AGLP030) utilize a 128-bit flash-based lock and a separate AES key to provide the highest level of security in the FPGA industry for programmed intellectual property and configuration data. In addition, all FlashROM data in IGLOO PLUS devices can be encrypted prior to loading, using the industry-leading AES-128 (FIPS192) bit block cipher encryption standard. AES was adopted by the National Institute of Standards and Technology (NIST) in 2000 and replaces the 1977 DES standard. IGLOO PLUS devices have a built-in AES decryption engine and a flash-based AES key that make them the most comprehensive programmable logic device security solution available today. IGLOO PLUS devices with AES-based security provide a high level of protection for secure, remote field updates over public networks such as the Internet, and ensure that valuable IP remains out of the hands of system overbuilders, system cloners, and IP thieves.

Security, built into the FPGA fabric, is an inherent component of the IGLOO PLUS family. The flash cells are located beneath seven metal layers, and many device design and layout techniques have been used to make invasive attacks extremely difficult. The IGLOO PLUS family, with FlashLock and AES security, is unique in being highly resistant to both invasive and noninvasive attacks. Your valuable IP is protected with industry-standard security, making remote ISP possible. An IGLOO PLUS device provides the best available security for programmable logic designs.

Single Chip

Flash-based FPGAs store their configuration information in on-chip flash cells. Once programmed, the configuration data is an inherent part of the FPGA structure, and no external configuration data needs to be loaded at system power-up (unlike SRAM-based FPGAs). Therefore, flash-based IGLOO PLUS FPGAs do not require system configuration components such as EEPROMs or microcontrollers to load device configuration data. This reduces bill-of-materials costs and PCB area, and increases security and system reliability.

The IGLOO PLUS devices can be operated with a 1.2 V or 1.5 V single-voltage supply for core and I/Os, eliminating the need for additional supplies while minimizing total power consumption.

Instant On

Flash-based IGLOO PLUS devices support Level 0 of the Instant On classification standard. This feature helps in system component initialization, execution of critical tasks before the processor wakes up, setup and configuration of memory blocks, clock generation, and bus activity management. The Instant On feature of flash-based IGLOO PLUS devices greatly simplifies total system design and reduces total system cost, often eliminating the need for CPLDs and clock generation PLLs. In addition, glitches and brownouts in system power will not corrupt the IGLOO PLUS device's flash configuration, and unlike SRAM-based FPGAs, the device will not have to be reloaded when system power is restored. This enables the reduction or complete removal of the configuration PROM, expensive voltage monitor, brownout detection, and clock generator devices from the PCB design. Flash-based IGLOO PLUS devices simplify total system design and reduce cost and design risk while increasing system reliability and improving system initialization time.

IGLOO PLUS flash FPGAs allow the user to quickly enter and exit Flash*Freeze mode. This is done almost instantly (within 1 µs), and the device retains configuration and data in registers and RAM. Unlike SRAM-based FPGAs, the device does not need to reload configuration and design state from external memory components; instead, it retains all necessary information to resume operation immediately.

Reduced Cost of Ownership

Advantages to the designer extend beyond low unit cost, performance, and ease of use. Unlike SRAMbased FPGAs, flash-based IGLOO PLUS devices allow all functionality to be Instant On; no external boot PROM is required. On-board security mechanisms prevent access to all the programming information and enable secure remote updates of the FPGA logic. Designers can perform secure remote in-system reprogramming to support future design iterations and field upgrades with confidence that valuable intellectual property cannot be compromised or copied. Secure ISP can be performed using the industrystandard AES algorithm.





Note: *Not supported by AGLP030 devices

Figure 1-1 • IGLOO PLUS Device Architecture Overview with Four I/O Banks (AGLP030, AGLP060, and AGLP125)

Flash*Freeze Technology

The IGLOO PLUS device has an ultra-low power static mode, called Flash*Freeze mode, which retains all SRAM and register information and can still quickly return to normal operation. Flash*Freeze technology enables the user to quickly (within 1 μ s) enter and exit Flash*Freeze mode by activating the Flash*Freeze pin while all power supplies are kept at their original values. In addition, I/Os and global I/Os can still be driven and can be toggling without impact on power consumption, clocks can still be driven or can be toggling without impact on power consumption, and the device retains all core registers, SRAM information, and I/O states. I/Os can be individually configured to either hold their previous state or be tristated during Flash*Freeze mode. Alternatively, they can be set to a certain state using weak pull-up or pull-down I/O attribute configuration. No power is consumed by the I/O banks, clocks, JTAG pins, or PLL, and the device consumes as little as 5 μ W in this mode.

Flash*Freeze technology allows the user to switch to Active mode on demand, thus simplifying the power management of the device.

The Flash*Freeze pin (active low) can be routed internally to the core to allow the user's logic to decide when it is safe to transition to this mode. Refer to Figure 1-2 for an illustration of entering/exiting Flash*Freeze mode. It is also possible to use the Flash*Freeze pin as a regular I/O if Flash*Freeze mode usage is not planned.



Figure 1-2 • IGLOO PLUS Flash*Freeze Mode



2 – IGLOO PLUS DC and Switching Characteristics

General Specifications

Operating Conditions

Stresses beyond those listed in Table 2-1 may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Absolute Maximum Ratings are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the Recommended Operating Conditions specified in Table 2-2 on page 2-2 is not implied.

Table 2-1 •	Absolute	Maximum	Ratings
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Symbol	Parameter	Limits	Units
VCC	DC core supply voltage	–0.3 to 1.65	V
VJTAG	JTAG DC voltage	-0.3 to 3.75	V
VPUMP	Programming voltage	-0.3 to 3.75	V
VCCPLL	Analog power supply (PLL)	–0.3 to 1.65	V
VCCI	DC I/O buffer supply voltage	-0.3 to 3.75	V
VI ¹	I/O input voltage	–0.3 V to 3.6 V	V
T _{STG} ²	Storage temperature	–65 to +150	°C
T _J ²	Junction temperature	+125	°C

Notes:

1. The device should be operated within the limits specified by the datasheet. During transitions, the input signal may undershoot or overshoot according to the limits shown in Table 2-4 on page 2-3.

2. For flash programming and retention maximum limits, refer to Table 2-3 on page 2-3, and for recommended operating limits, refer to Table 2-2 on page 2-2.

Power per I/O Pin

Table 2-13 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings

	VCCI (V)	Dynamic Power PAC9 (μW/MHz) ¹
Single-Ended		
3.3 V LVTTL / 3.3 V LVCMOS	3.3	16.26
3.3 V LVTTL / 3.3 V LVCMOS – Schmitt Trigger	3.3	18.95
3.3 V LVCMOS Wide Range ²	3.3	16.26
3.3 V LVCMOS Wide Range ² – Schmitt Trigger	3.3	18.95
2.5 V LVCMOS	2.5	4.59
2.5 V LVCMOS – Schmitt Trigger	2.5	6.01
1.8 V LVCMOS	1.8	1.61
1.8 V LVCMOS – Schmitt Trigger	1.8	1.70
1.5 V LVCMOS (JESD8-11)	1.5	0.96
1.5 V LVCMOS (JESD8-11) – Schmitt Trigger	1.5	0.90
1.2 V LVCMOS ³	1.2	0.55
1.2 V LVCMOS ³ – Schmitt Trigger	1.2	0.47
1.2 V LVCMOS Wide Range ³	1.2	0.55
1.2 V LVCMOS Wide Range ³ – Schmitt Trigger	1.2	0.47

Notes:

1. PAC9 is the total dynamic power measured on VCCI.

2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.

3. Applicable for IGLOO PLUS V2 devices only, operating at VCCI \geq VCC.

Table 2-14 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings¹

	C _{LOAD} (pF)	VCCI (V)	Dynamic Power PAC10 (μW/MHz) ²
Single-Ended			
3.3 V LVTTL / 3.3 V LVCMOS	5	3.3	127.11
3.3 V LVCMOS Wide Range ³	5	3.3	127.11
2.5 V LVCMOS	5	2.5	70.71
1.8 V LVCMOS	5	1.8	35.57
1.5 V LVCMOS (JESD8-11)	5	1.5	24.30
1.2 V LVCMOS ⁴	5	1.2	15.22
1.2 V LVCMOS Wide Range ⁴	5	1.2	15.22

Notes:

1. Dynamic power consumption is given for standard load and software default drive strength and output slew.

2. PAC10 is the total dynamic power measured on VCCI.

3. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.

4. Applicable for IGLOO PLUS V2 devices only, operating at VCCI \geq VCC.



IGLOO PLUS DC and Switching Characteristics

Power Calculation Methodology

This section describes a simplified method to estimate power consumption of an application. For more accurate and detailed power estimations, use the SmartPower tool in Libero SoC software.

The power calculation methodology described below uses the following variables:

- The number of PLLs as well as the number and the frequency of each output clock generated
- · The number of combinatorial and sequential cells used in the design
- · The internal clock frequencies
- · The number and the standard of I/O pins used in the design
- The number of RAM blocks used in the design
- Toggle rates of I/O pins as well as VersaTiles—guidelines are provided in Table 2-19 on page 2-14.
- Enable rates of output buffers—guidelines are provided for typical applications in Table 2-20 on page 2-14.
- Read rate and write rate to the memory—guidelines are provided for typical applications in Table 2-20 on page 2-14. The calculation should be repeated for each clock domain defined in the design.

Methodology

Total Power Consumption—PTOTAL

 $P_{TOTAL} = P_{STAT} + P_{DYN}$

P_{STAT} is the total static power consumption.

P_{DYN} is the total dynamic power consumption.

Total Static Power Consumption—PSTAT

P_{STAT} = (PDC1 or PDC2 or PDC3) + N_{BANKS} * PDC5

 N_{BANKS} is the number of I/O banks powered in the design.

Total Dynamic Power Consumption—P_{DYN}

P_{DYN} = P_{CLOCK} + P_{S-CELL} + P_{C-CELL} + P_{NET} + P_{INPUTS} + P_{OUTPUTS} + P_{MEMORY} + P_{PLL}

Global Clock Contribution—P_{CLOCK}

 $P_{CLOCK} = (PAC1 + N_{SPINE}*PAC2 + N_{ROW}*PAC3 + N_{S-CELL}*PAC4) * F_{CLK}$

N_{SPINE} is the number of global spines used in the user design—guidelines are provided in the "Spine Architecture" section of the Global Resources chapter in the *IGLOO PLUS FPGA Fabric User's Guide*.

N_{ROW} is the number of VersaTile rows used in the design—guidelines are provided in the "Spine Architecture" section of the Global Resources chapter in the *IGLOO PLUS FPGA Fabric User's Guide*.

F_{CLK} is the global clock signal frequency.

N_{S-CELL} is the number of VersaTiles used as sequential modules in the design.

PAC1, PAC2, PAC3, and PAC4 are device-dependent.

Sequential Cells Contribution—P_{S-CELL}

 $P_{S-CELL} = N_{S-CELL} * (PAC5 + \alpha_1 / 2 * PAC6) * F_{CLK}$

 $N_{S\mbox{-}CELL}$ is the number of VersaTiles used as sequential modules in the design. When a multi-tile sequential cell is used, it should be accounted for as 1.

 α_{1} is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-19 on page 2-14.

F_{CLK} is the global clock signal frequency.

Combinatorial Cells Contribution—P_{C-CELL}

 $P_{C-CELL} = N_{C-CELL} * \alpha_1 / 2 * PAC7 * F_{CLK}$

N_{C-CELL} is the number of VersaTiles used as combinatorial modules in the design.

 α_{1} is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-19 on page 2-14.

 $\mathsf{F}_{\mathsf{CLK}}$ is the global clock signal frequency.

Routing Net Contribution—P_{NET}

 $P_{NET} = (N_{S-CELL} + N_{C-CELL}) * \alpha_1 / 2 * PAC8 * F_{CLK}$

N_{S-CELL} is the number of VersaTiles used as sequential modules in the design.

 N_{C-CELL} is the number of VersaTiles used as combinatorial modules in the design.

 α_{1} is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-19 on page 2-14.

 $\mathsf{F}_{\mathsf{CLK}}$ is the global clock signal frequency.

I/O Input Buffer Contribution—PINPUTS

 $P_{INPUTS} = N_{INPUTS} * \alpha_2 / 2 * P_{AC9} * F_{CLK}$

N_{INPUTS} is the number of I/O input buffers used in the design.

 α_2 is the I/O buffer toggle rate—guidelines are provided in Table 2-19 on page 2-14.

 F_{CLK} is the global clock signal frequency.

I/O Output Buffer Contribution—POUTPUTS

 $P_{OUTPUTS} = N_{OUTPUTS} * \alpha_2 / 2 * \beta_1 * PAC10 * F_{CLK}$

N_{OUTPUTS} is the number of I/O output buffers used in the design.

 α_2 is the I/O buffer toggle rate—guidelines are provided in Table 2-19 on page 2-14.

 β_1 is the I/O buffer enable rate—guidelines are provided in Table 2-20 on page 2-14.

F_{CLK} is the global clock signal frequency.

RAM Contribution—P_{MEMORY}

 $\mathsf{P}_{\mathsf{MEMORY}} = \mathsf{P}_{\mathsf{AC11}} * \mathsf{N}_{\mathsf{BLOCKS}} * \mathsf{F}_{\mathsf{READ-CLOCK}} * \beta_2 + \mathsf{PAC12} * \mathsf{N}_{\mathsf{BLOCK}} * \mathsf{F}_{\mathsf{WRITE-CLOCK}} * \beta_3$

N_{BLOCKS} is the number of RAM blocks used in the design.

 $\mathsf{F}_{\mathsf{READ}\text{-}\mathsf{CLOCK}}$ is the memory read clock frequency.

 β_2 is the RAM enable rate for read operations.

F_{WRITE-CLOCK} is the memory write clock frequency.

 β_3 is the RAM enable rate for write operations—guidelines are provided in Table 2-20 on page 2-14.

PLL Contribution—PPLL

 $P_{PLL} = PDC4 + PAC1_3 * F_{CLKOUT}$

F_{CLKOUT} is the output clock frequency.¹

Guidelines

Toggle Rate Definition

A toggle rate defines the frequency of a net or logic element relative to a clock. It is a percentage. If the toggle rate of a net is 100%, this means that this net switches at half the clock frequency. Below are some examples:

- The average toggle rate of a shift register is 100% because all flip-flop outputs toggle at half of the clock frequency.
- The average toggle rate of an 8-bit counter is 25%:

If a PLL is used to generate more than one output clock, include each output clock in the formula by adding its corresponding contribution (P_{AC13}* F_{CLKOUT} product) to the total PLL contribution.

I/O Standard	Drive Strength	Equivalent Software Default Drive Strength Option ¹	Slew Rate	Capacitive Load (pF)	External Resistor (Ω)	t _{воит}	top	t _{DIN}	t _P V)	tpys	teour	t _{zı}	t _{zн}	t _{LZ}	t _{HZ}	Units
3.3 V LVTTL / 3.3 V LVCMOS	12 mA	12 mA	High	5 pF	-	0.98	2.31	0.19	0.99	1.37	0.67	2.34	1.86	2.65	3.38	ns
3.3 V LVCMOS Wide Range ²	100 µA	12 mA	High	5 pF	-	0.98	3.21	0.19	1.32	1.92	0.67	3.21	2.52	3.73	4.73	ns
2.5 V LVCMOS	12 mA	12 mA	High	5 pF	-	0.98	2.29	0.19	1.19	1.40	0.67	2.32	1.94	2.65	3.27	ns
1.8 V LVCMOS	8 mA	8 mA	High	5 pF	-	0.98	2.45	0.19	1.12	1.61	0.67	2.48	2.16	2.71	3.16	ns
1.5 V LVCMOS	4 mA	4 mA	High	5 pF	-	0.98	2.71	0.19	1.26	1.80	0.67	2.75	2.39	2.78	3.15	ns
1.2 V LVCMOS	2 mA	2 mA	High	5 pF	-	0.98	3.38	0.19	1.57	2.34	0.67	3.26	2.78	2.99	3.24	ns
1.2 V LVCMOS Wide Range ³	100 µA	2 mA	High	5 pF	_	0.98	3.38	0.19	1.57	2.34	0.67	3.26	2.78	2.99	3.24	ns

Table 2-26 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed GradeCommercial-Case Conditions: TJ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V

Notes:

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.

2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.

All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification.
For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

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IGLOO PLUS DC and Switching Characteristics

Timing Characteristics

Applies to 1.5 V DC Core Voltage

Table 2-36 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage Commercial-Case Conditions: T₁ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{zH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.97	3.94	0.18	0.85	1.15	0.66	4.02	3.46	1.82	1.87	ns
4 mA	STD	0.97	3.94	0.18	0.85	1.15	0.66	4.02	3.46	1.82	1.87	ns
6 mA	STD	0.97	3.20	0.18	0.85	1.15	0.66	3.27	2.94	2.04	2.27	ns
8 mA	STD	0.97	3.20	0.18	0.85	1.15	0.66	3.27	2.94	2.04	2.27	ns
12 mA	STD	0.97	2.72	0.18	0.85	1.15	0.66	2.78	2.57	2.20	2.53	ns
16 mA	STD	0.97	2.72	0.18	0.85	1.15	0.66	2.78	2.57	2.20	2.53	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-37 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{zH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.97	2.36	0.18	0.85	1.15	0.66	2.41	1.90	1.82	1.98	ns
4 mA	STD	0.97	2.36	0.18	0.85	1.15	0.66	2.41	1.90	1.82	1.98	ns
6 mA	STD	0.97	1.96	0.18	0.85	1.15	0.66	2.01	1.56	2.04	2.38	ns
8 mA	STD	0.97	1.96	0.18	0.85	1.15	0.66	2.01	1.56	2.04	2.38	ns
12 mA	STD	0.97	1.76	0.18	0.85	1.15	0.66	1.80	1.39	2.20	2.64	ns
16 mA	STD	0.97	1.76	0.18	0.85	1.15	0.66	1.80	1.39	2.20	2.64	ns

Notes:

1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

2. Software default selection highlighted in gray.

Applies to 1.2 V DC Core Voltage

Table 2-38 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.2 V DC Core VoltageCommercial-Case Conditions: TJ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{zH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.98	4.56	0.19	0.99	1.37	0.67	4.63	3.98	2.26	2.57	ns
4 mA	STD	0.98	4.56	0.19	0.99	1.37	0.67	4.63	3.98	2.26	2.57	ns
6 mA	STD	0.98	3.80	0.19	0.99	1.37	0.67	3.96	3.45	2.49	2.98	ns
8 mA	STD	0.98	3.80	0.19	0.99	137	0.67	3.86	3.45	2.49	2.98	ns
12 mA	STD	0.98	3.31	0.19	0.99	1.37	0.67	3.36	3.07	2.65	3.25	ns
16 mA	STD	0.98	3.31	0.19	0.99	1.37	0.67	3.36	3.07	2.65	3.25	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.



Output Register

Figure 2-15 • Output Register Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-76 • Output Data Register Propagation DelaysCommercial-Case Conditions: TJ = 70°C, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t _{OCLKQ}	Clock-to-Q of the Output Data Register	0.66	ns
tosud	Data Setup Time for the Output Data Register	0.33	ns
t _{OHD}	Data Hold Time for the Output Data Register	0.00	ns
t _{OCLR2Q}	Asynchronous Clear-to-Q of the Output Data Register	0.82	ns
t _{OPRE2Q}	Asynchronous Preset-to-Q of the Output Data Register	0.88	ns
t _{OREMCLR}	Asynchronous Clear Removal Time for the Output Data Register	0.00	ns
t _{ORECCLR}	Asynchronous Clear Recovery Time for the Output Data Register	0.24	ns
t _{OREMPRE}	Asynchronous Preset Removal Time for the Output Data Register	0.00	ns
t _{ORECPRE}	Asynchronous Preset Recovery Time for the Output Data Register	0.24	ns
t _{OWCLR}	Asynchronous Clear Minimum Pulse Width for the Output Data Register	0.19	ns
t _{OWPRE}	Asynchronous Preset Minimum Pulse Width for the Output Data Register	0.19	ns
t _{OCKMPWH}	Clock Minimum Pulse Width High for the Output Data Register	0.31	ns
t _{OCKMPWL}	Clock Minimum Pulse Width Low for the Output Data Register	0.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

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IGLOO PLUS DC and Switching Characteristics

1.2 V DC Core Voltage

Table 2-79 • Output Enable Register Propagation DelaysCommercial-Case Conditions: TJ = 70°C, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{OECLKQ}	Clock-to-Q of the Output Enable Register	1.06	ns
tOESUD	Data Setup Time for the Output Enable Register	0.52	ns
t _{OEHD}	Data Hold Time for the Output Enable Register	0.00	ns
t _{OECLR2Q}	Asynchronous Clear-to-Q of the Output Enable Register	1.25	ns
t _{OEPRE2Q}	Asynchronous Preset-to-Q of the Output Enable Register	1.36	ns
t _{OEREMCLR}	Asynchronous Clear Removal Time for the Output Enable Register	0.00	ns
t _{OERECCLR}	Asynchronous Clear Recovery Time for the Output Enable Register	0.24	ns
t _{OEREMPRE}	Asynchronous Preset Removal Time for the Output Enable Register	0.00	ns
t _{OERECPRE}	Asynchronous Preset Recovery Time for the Output Enable Register	0.24	ns
t _{OEWCLR}	Asynchronous Clear Minimum Pulse Width for the Output Enable Register	0.19	ns
t _{OEWPRE}	Asynchronous Preset Minimum Pulse Width for the Output Enable Register	0.19	ns
t _{OECKMPWH}	Clock Minimum Pulse Width High for the Output Enable Register	0.31	ns
t _{OECKMPWL}	Clock Minimum Pulse Width Low for the Output Enable Register	0.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-6 for derating values.

VersaTile Characteristics

VersaTile Specifications as a Combinatorial Module

The IGLOO PLUS library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the *Fusion, IGLOO/e, and ProASIC3/ E Macro Library Guide*.



Figure 2-17 • Sample of Combinatorial Cells

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IGLOO PLUS DC and Switching Characteristics

1.2 V DC Core Voltage

Table 2-83 • Register Delays

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{CLKQ}	Clock-to-Q of the Core Register	1.61	ns
t _{SUD}	Data Setup Time for the Core Register	1.17	ns
t _{HD}	Data Hold Time for the Core Register	0.00	ns
t _{SUE}	Enable Setup Time for the Core Register	1.29	ns
t _{HE}	Enable Hold Time for the Core Register	0.00	ns
t _{CLR2Q}	Asynchronous Clear-to-Q of the Core Register	0.87	ns
t _{PRE2Q}	Asynchronous Preset-to-Q of the Core Register	0.89	ns
t _{REMCLR}	Asynchronous Clear Removal Time for the Core Register	0.00	ns
t _{RECCLR}	Asynchronous Clear Recovery Time for the Core Register	0.24	ns
t _{REMPRE}	Asynchronous Preset Removal Time for the Core Register	0.00	ns
t _{RECPRE}	Asynchronous Preset Recovery Time for the Core Register	0.24	ns
t _{WCLR}	Asynchronous Clear Minimum Pulse Width for the Core Register	0.46	ns
t _{WPRE}	Asynchronous Preset Minimum Pulse Width for the Core Register	0.46	ns
t _{CKMPWH}	Clock Minimum Pulse Width High for the Core Register	0.95	ns
t _{CKMPWL}	Clock Minimum Pulse Width Low for the Core Register	0.95	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-6 for derating values.

Microsemi.

IGLOO PLUS DC and Switching Characteristics







Figure 2-27 • RAM Write, Output as Write Data (WMODE = 1). Applicable to RAM4K9 only.

IGLOO PLUS DC and Switching Characteristics



Figure 2-32 • FIFO Reset





JTAG 1532 Characteristics

JTAG timing delays do not include JTAG I/Os. To obtain complete JTAG timing, add I/O buffer delays to the corresponding standard selected; refer to the I/O timing characteristics in the "User I/O Characteristics" section on page 2-15 for more details.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-100 • JTAG 1532

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t _{DISU}	Test Data Input Setup Time	1.00	ns
t _{DIHD}	Test Data Input Hold Time	2.00	ns
t _{TMSSU}	Test Mode Select Setup Time	1.00	ns
t _{TMDHD}	Test Mode Select Hold Time	2.00	ns
t _{TCK2Q}	Clock to Q (data out)	8.00	ns
t _{RSTB2Q}	Reset to Q (data out)	25.00	ns
F _{TCKMAX}	TCK Maximum Frequency	15	MHz
t _{TRSTREM}	ResetB Removal Time	0.58	ns
t _{TRSTREC}	ResetB Recovery Time	0.00	ns
t _{TRSTMPW}	ResetB Minimum Pulse	TBD	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-101 • JTAG 1532

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{DISU}	Test Data Input Setup Time	1.50	ns
t _{DIHD}	Test Data Input Hold Time	3.00	ns
t _{TMSSU}	Test Mode Select Setup Time	1.50	ns
t _{TMDHD}	Test Mode Select Hold Time	3.00	ns
t _{TCK2Q}	Clock to Q (data out)	11.00	ns
t _{RSTB2Q}	Reset to Q (data out)	30.00	ns
F _{TCKMAX}	TCK Maximum Frequency	9.00	MHz
t _{TRSTREM}	ResetB Removal Time	1.18	ns
t _{TRSTREC}	ResetB Recovery Time	0.00	ns
t _{TRSTMPW}	ResetB Minimum Pulse	TBD	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.



VQ128				
Pin Number	AGLP030 Function			
106	IO26RSB0			
107	IO25RSB0			
108	IO23RSB0			
109	IO22RSB0			
110	IO21RSB0			
111	IO19RSB0			
112	IO18RSB0			
113	VCC			
114	IO17RSB0			
115	IO16RSB0			
116	IO14RSB0			
117	IO13RSB0			
118	IO12RSB0			
119	IO10RSB0			
120	IO09RSB0			
121	VCCIB0			
122	GND			
123	IO07RSB0			
124	IO05RSB0			
125	IO03RSB0			
126	IO02RSB0			
127	IO01RSB0			
128	IO00RSB0			



Package Pin Assignments

CS201		CS201		CS201	
Pin Number	AGLP060 Function	Pin Number	AGLP060 Function	Pin Number	AGLP060 Function
A1	IO150RSB3	C6	IO07RSB0	F3	IO145RSB3
A2	GAA0/IO00RSB0	C7	IO16RSB0	F4	IO147RSB3
A3	GAC0/IO04RSB0	C8	IO21RSB0	F6	GND
A4	IO08RSB0	C9	IO28RSB0	F7	VCC
A5	IO11RSB0	C10	GBB1/IO33RSB0	F8	VCCIB0
A6	IO15RSB0	C11	GBA1/IO35RSB0	F9	VCCIB0
A7	IO17RSB0	C12	GBB2/IO38RSB1	F10	VCCIB0
A8	IO18RSB0	C13	GND	F12	IO47RSB1
A9	IO22RSB0	C14	IO48RSB1	F13	IO45RSB1
A10	IO26RSB0	C15	IO39RSB1	F14	GCC1/IO52RSB1
A11	IO29RSB0	D1	IO146RSB3	F15	GCA1/IO56RSB1
A12	GBC1/IO31RSB0	D2	IO144RSB3	G1*	VCOMPLF
A13	GBA2/IO36RSB1	D3	IO148RSB3	G2	GFB0/IO137RSB3
A14	IO41RSB1	D4	GND	G3	GFC0/IO139RSB3
A15	NC	D5	GAB0/IO02RSB0	G4	IO143RSB3
B1	IO151RSB3	D6	GAC1/IO05RSB0	G6	VCCIB3
B2	GAB2/IO154RSB3	D7	IO14RSB0	G7	GND
B3	IO06RSB0	D8	IO19RSB0	G8	VCC
B4	IO09RSB0	D9	GBC0/IO30RSB0	G9	GND
B5	IO13RSB0	D10	GBB0/IO32RSB0	G10	GND
B6	IO10RSB0	D11	GBA0/IO34RSB0	G12	IO50RSB1
B7	IO12RSB0	D12	GND	G13	GCB1/IO54RSB1
B8	IO20RSB0	D13	GBC2/IO40RSB1	G14	GCC2/IO60RSB1
B9	IO23RSB0	D14	IO51RSB1	G15	GCA2/IO58RSB1
B10	IO25RSB0	D15	IO44RSB1	H1*	VCCPLF
B11	IO24RSB0	E1	IO142RSB3	H2	GFA1/IO136RSB3
B12	IO27RSB0	E2	IO149RSB3	H3	GFB1/IO138RSB3
B13	IO37RSB1	E3	IO153RSB3	H4	NC
B14	IO46RSB1	E4	GAC2/IO152RSB3	H6	VCCIB3
B15	IO42RSB1	E12	IO43RSB1	H7	GND
C1	IO155RSB3	E13	IO49RSB1	H8	VCC
C2	GAA2/IO156RSB3	E14	GCC0/IO53RSB1	H9	GND
C3	GND	E15	GCB0/IO55RSB1	H10	VCCIB1
C4	GAA1/IO01RSB0	F1	IO141RSB3	H12	GCB2/IO59RSB1
C5	GAB1/IO03RSB0	F2	GFC1/IO140RSB3	H13	GCA0/IO57RSB1

Note: *Pin numbers G1 and H1 must be connected to ground because a PLL is not supported for AGLP060-CS/G201.



Package Pin Assignments

CS289		CS289		CS289	
Pin Number	AGLP060 Function	Pin Number	AGLP060 Function	Pin Number	AGLP060 Function
A1	GAB1/IO03RSB0	C5	VCCIB0	E9	IO22RSB0
A2	NC	C6	IO09RSB0	E10	IO26RSB0
A3	NC	C7	IO13RSB0	E11	VCCIB0
A4	GND	C8	IO15RSB0	E12	NC
A5	IO10RSB0	C9	IO21RSB0	E13	GBB1/IO33RSB0
A6	IO14RSB0	C10	GND	E14	GBA2/IO36RSB1
A7	IO16RSB0	C11	IO29RSB0	E15	GBB2/IO38RSB1
A8	IO18RSB0	C12	NC	E16	VCCIB1
A9	GND	C13	NC	E17	IO44RSB1
A10	IO23RSB0	C14	NC	F1	GFC1/IO140RSB3
A11	IO27RSB0	C15	GND	F2	IO142RSB3
A12	NC	C16	GBA0/IO34RSB0	F3	IO149RSB3
A13	NC	C17	IO39RSB1	F4	VCCIB3
A14	GND	D1	IO150RSB3	F5	GAB2/IO154RSB3
A15	NC	D2	IO151RSB3	F6	IO153RSB3
A16	NC	D3	GND	F7	NC
A17	GBC0/IO30RSB0	D4	GAB0/IO02RSB0	F8	IO08RSB0
B1	GAA1/IO01RSB0	D5	NC	F9	IO12RSB0
B2	GND	D6	NC	F10	NC
B3	NC	D7	NC	F11	NC
B4	NC	D8	GND	F12	NC
B5	IO07RSB0	D9	IO20RSB0	F13	GBC2/IO40RSB1
B6	NC	D10	IO25RSB0	F14	GND
B7	VCCIB0	D11	NC	F15	IO43RSB1
B8	IO17RSB0	D12	NC	F16	IO46RSB1
B9	IO19RSB0	D13	GND	F17	IO45RSB1
B10	IO24RSB0	D14	GBB0/IO32RSB0	G1	GFC0/IO139RSB3
B11	IO28RSB0	D15	GBA1/IO35RSB0	G2	GND
B12	VCCIB0	D16	IO37RSB1	G3	IO144RSB3
B13	NC	D17	IO42RSB1	G4	IO145RSB3
B14	NC	E1	VCCIB3	G5	IO146RSB3
B15	NC	E2	IO147RSB3	G6	IO148RSB3
B16	GBC1/IO31RSB0	E3	GAC2/IO152RSB3	G7	GND
B17	GND	E4	GAA2/IO156RSB3	G8	GND
C1	IO155RSB3	E5	GAC1/IO05RSB0	G9	VCC
C2	GAA0/IO00RSB0	E6	NC	G10	GND
C3	GAC0/IO04RSB0	E7	IO06RSB0	G11	GND
C4	NC	E8	IO11RSB0	G12	IO48RSB1

IGLOO PLUS Low Power Flash FPGAs

CS289		CS289		CS289	
Pin Number	AGLP125 Function	Pin Number	AGLP125 Function	Pin Number	AGLP125 Function
A1	GAB1/IO03RSB0	C5	VCCIB0	E9	IO32RSB0
A2	IO11RSB0	C6	IO17RSB0	E10	IO36RSB0
A3	IO08RSB0	C7	IO23RSB0	E11	VCCIB0
A4	GND	C8	IO27RSB0	E12	IO56RSB0
A5	IO19RSB0	C9	IO33RSB0	E13	GBB1/IO60RSB0
A6	IO24RSB0	C10	GND	E14	GBA2/IO63RSB1
A7	IO26RSB0	C11	IO43RSB0	E15	GBB2/IO65RSB1
A8	IO30RSB0	C12	IO45RSB0	E16	VCCIB1
A9	GND	C13	IO50RSB0	E17	IO73RSB1
A10	IO35RSB0	C14	IO52RSB0	F1	GFC1/IO194RSB3
A11	IO38RSB0	C15	GND	F2	IO196RSB3
A12	IO40RSB0	C16	GBA0/IO61RSB0	F3	IO202RSB3
A13	IO42RSB0	C17	IO68RSB1	F4	VCCIB3
A14	GND	D1	IO204RSB3	F5	GAB2/IO209RSB3
A15	IO48RSB0	D2	IO205RSB3	F6	IO208RSB3
A16	IO54RSB0	D3	GND	F7	IO14RSB0
A17	GBC0/IO57RSB0	D4	GAB0/IO02RSB0	F8	IO20RSB0
B1	GAA1/IO01RSB0	D5	IO07RSB0	F9	IO25RSB0
B2	GND	D6	IO10RSB0	F10	IO29RSB0
B3	IO06RSB0	D7	IO18RSB0	F11	IO51RSB0
B4	IO13RSB0	D8	GND	F12	IO53RSB0
B5	IO15RSB0	D9	IO34RSB0	F13	GBC2/IO67RSB1
B6	IO21RSB0	D10	IO41RSB0	F14	GND
B7	VCCIB0	D11	IO47RSB0	F15	IO75RSB1
B8	IO28RSB0	D12	IO55RSB0	F16	IO71RSB1
B9	IO31RSB0	D13	GND	F17	IO77RSB1
B10	IO37RSB0	D14	GBB0/IO59RSB0	G1	GFC0/IO193RSB3
B11	IO39RSB0	D15	GBA1/IO62RSB0	G2	GND
B12	VCCIB0	D16	IO66RSB1	G3	IO198RSB3
B13	IO44RSB0	D17	IO70RSB1	G4	IO203RSB3
B14	IO46RSB0	E1	VCCIB3	G5	IO201RSB3
B15	IO49RSB0	E2	IO200RSB3	G6	IO206RSB3
B16	GBC1/IO58RSB0	E3	GAC2/IO207RSB3	G7	GND
B17	GND	E4	GAA2/IO211RSB3	G8	GND
C1	IO210RSB3	E5	GAC1/IO05RSB0	G9	VCC
C2	GAA0/IO00RSB0	E6	IO12RSB0	G10	GND
C3	GAC0/IO04RSB0	E7	IO16RSB0	G11	GND
C4	IO09RSB0	E8	IO22RSB0	G12	IO72RSB1



Datasheet Information

Revision	Changes	Page
Revision 10 (Apr 2009) Product Brief v1.5 DC and Switching Characteristics Advance v0.5	The –F speed grade is no longer offered for IGLOO PLUS devices. References to it have been removed from the document. The speed grade column and note regarding –F speed grade were removed from "IGLOO PLUS Ordering Information". The "Speed Grade and Temperature Grade Matrix" section was removed.	III, IV
Revision 9 (Feb 2009) Product Brief v1.4	The "Advanced I/O" section was revised to add two bullets regarding support of wide range power supply voltage.	I
	The "I/Os with Advanced I/O Standards" section was revised to add 3.0 V wide range to the list of supported voltages. The "Wide Range I/O Support" section is new.	1-7
Revision 8 (Jan 2009) Packaging v1.5	The "CS201" pin table was revised to add a note regarding pins G1 and H1.	4-8
Revision 7 (Dec 2008) Product Brief v1.3	A note was added to IGLOO PLUS Devices: "AGLP060 in CS201 does not support the PLL."	I
	Table 2 • IGLOO PLUS FPGAs Package Size Dimensions was updated tochange the nominal size of VQ176 from 100 to 400 mm².	II
Revision 6 (Oct 2008) DC and Switching Characteristics Advance v0.4	Data was revised significantly in the following tables: Table 2-25 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed Grade, Commercial-Case Conditions: T _J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V	2-22, 2-33
	Table 2-26 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed Grade Commercial-Case Conditions: $T_J = 70^{\circ}$ C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V Table 2-50 • 2.5 LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage Table 2-51 • 2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage	
Revision 5 (Aug 2008) Product Brief v1.2	The VQ128 and VQ176 packages were added to Table 1 • IGLOO PLUS Product Family, the "I/Os Per Package ¹ " table, Table 2 • IGLOO PLUS FPGAs Package Size Dimensions, "IGLOO PLUS Ordering Information", and the "Temperature Grade Offerings" table.	I to IV
Packaging v1.4	The "VQ128" package drawing and pin table are new.	4-2
	The "VQ176" package drawing and pin table are new.	4-5
Revision 4 (Jul 2008) Product Brief v1.1 DC and Switching Characteristics Advance v0.3	As a result of the Libero IDE v8.4 release, Actel now offers a wide range of core voltage support. The document was updated to change $1.2 \text{ V} / 1.5 \text{ V}$ to 1.2 V to 1.5 V .	N/A
Revision 3 (Jun 2008) DC and Switching Characteristics Advance v0.2	Tables have been updated to reflect default values in the software. The default I/O capacitance is 5 pF. Tables have been updated to include the LVCMOS 1.2 V I/O set.	N/A
	Table note 3 was updated in Table 2-2 • Recommended Operating Conditions ^{1,2} to add the sentence, "VCCI should be at the same voltage within a given I/O bank." References to table notes 5, 6, 7, and 8 were added. Reference to table note 3 was removed from VPUMP Operation and placed next to VCC.	2-2
	Table 2-4 Overshoot and Undershoot Limits ¹ was revised to remove "as measured on quiet I/Os" from the title. Table note 2 was revised to remove "estimated SSO density over cycles." Table note 3 was deleted.	2-3